EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	212	laser and (mirror$1 or reflec$4) and (gain or active) and (heat near3 conduct$4) and (thermal$3 near3 conduct$5) and (pressure with bond$4)	US-PGPUB; USPAT	AND	ON	2006/06/13 14:39
L2	74	laser and (mirror$1 or reflec$4) and (gain or active) and (heat near3 (sink or conduct$4)) and (thermal$3 near3 conduct$5) and (pressure with bond$4 with adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 14:40
L4	1	laser and (mirror$1 or reflec$4) and (gain or active) and (heat near3 (sink or conduct$4)) and (thermal$3 near3 conduct$5) and (pressure with bond$4 with adhesive) and "372"/$.ccls.	US-PGPUB; USPAT	AND	ON	2006/06/13 14:40
L3	22	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and (heat near3 (sink or conduct$4)) and (thermal$3 near3 conduct$5) and (pressure with bond$4 with adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 14:42
L5	22	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and (heat near3 (sink or conduct$4 or element)) and (thermal$3 near3 conduct$5) and (pressure with bond$4 with adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 14:45
L6	49	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and (heat near3 (sink or conduct$4 or element)) and (pressure with bond$4 with adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 14:45
L7	1	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) with (pressure with bond$4 with adhesive))	US-PGPUB; USPAT	AND	ON	2006/06/13 14:49
L10	75	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) same (contact near3 bond$4))	US-PGPUB; USPAT	AND	ON	2006/06/13 14:52
L8	2	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) same (pressure with bond$4 with adhesive))	US-PGPUB; USPAT	AND	ON	2006/06/13 14:53
L12	0	laser and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) same (pressure with bond$4 with ((free or without) near2 adhesive)))	US-PGPUB; USPAT	AND	ON	2006/06/13 14:53
L13	1	((heat near3 (sink or conduct$4 or element)) same (pressure with bond$4 with ((free or without) near2 adhesive)))	US-PGPUB; USPAT	AND	ON	2006/06/13 14:53
L11	41	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) with (contact near3 bond$4))	US-PGPUB; USPAT	AND	ON	2006/06/13 14:57
L15	1	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) with (contact near3 bond$4)) and ((free or without or any) near2 adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 14:58
L14	1	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) with (contact near3 bond$4)) and ((free or without) near2 adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 15:00
L17	1	("5,846,638").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/13 15:03
L16	3	((semiconductor or diode or (solid near3 state)) near3 laser) and (mirror$1 or reflec$4) and (gain or active) and ((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) and ((free or without) near2 adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 15:08
L18	7	laser and ((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) and ((free or without) near2 adhesive)	US-PGPUB; USPAT	AND	ON	2006/06/13 15:13
L20	7	laser and ((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) and ((free or without) near2 adhes$4)	US-PGPUB; USPAT	AND	ON	2006/06/13 15:14
L22	1	((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) same ((free or without) near2 adhes$4)	US-PGPUB; USPAT	AND	ON	2006/06/13 15:15

L23	1	((((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) same ((free or without) near2 adhes$4))	US-PGPUB; USPAT	AND	ON	2006/06/13 15:15
L24	3	("5213868" | "5298791").PN. OR ("6086994").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2006/06/13 15:33
L21	21	((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) and ((free or without) near2 adhes$4)	US-PGPUB; USPAT	AND	ON	2006/06/13 15:44
L31	946	((heat-sink or (heat near6 (sink or conduct$4 or element))) same sapphire)	US-PGPUB; USPAT; IBM_TDB	AND	ON	2006/06/13 15:47
L32	424	((heat-sink or (heat near6 (sink or conduct$4 or element))) with sapphire)	US-PGPUB; USPAT; IBM_TDB	AND	ON	2006/06/13 15:47
L33	73	((heat-sink or (heat near6 (sink or conduct$4 or element))) with (sapphire and diamond))	US-PGPUB; USPAT; IBM_TDB	AND	ON	2006/06/13 15:50
L34	24	((heat-sink or (heat near6 (sink or conduct$4 or element))) with (sapphire and diamond)) and "372"/$.ccls.	US-PGPUB; USPAT; IBM_TDB	AND	ON	2006/06/13 15:50
L19	1	(((heat near3 (sink or conduct$4 or element)) same ((contact near3 bond$4) or contact-bond$4)) same ((free or without) near2 adhesive))	US-PGPUB; USPAT	AND	ON	2006/06/13 16:03
L35	230	((heat near3 (sink or conduct$4 or element)) same ((free or without) near2 adhesive))	US-PGPUB; USPAT	AND	ON	2006/06/13 16:03
L36	126	((heat near3 (sink or conduct$4 or element)) WITH ((free or without) near2 adhesive))	US-PGPUB; USPAT	AND	ON	2006/06/13 16:04